BGA Rework Soldering Station SMD BGA IR Infrared Preheating Soldering Hot Air Soldering

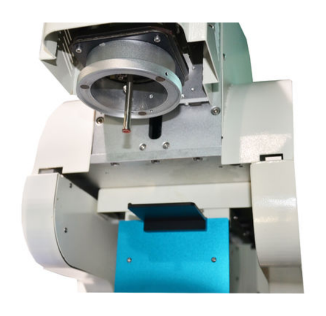
Our Product Introduction

Basic Information

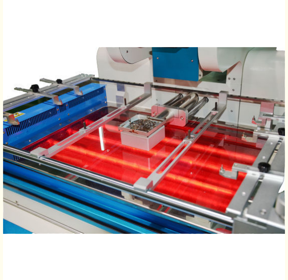
Place of Origin:	China
Brand Name:	WDS
Certification:	CE
Model Number:	WDS-850
Minimum Order Quantity:	1 UNIT
Packaging Details:	Wooden case
Delivery Time:	8-15 working days
Payment Terms:	T/T, Western Union, MoneyGram
Supply Ability:	150 UNITS PER MONTH

Product Specification

Warranty:	1 Year
Weight:	200KG
Voltage:	AC 220V
Current:	50/60hz
Dimensions:	L970*W7000*H830mm
Total Power:	8400W
PCB Size:	Max680*550mm Min 10*10 Mm
BGA Chip Size:	Max120*120mm Min 0.8*0.8mm
Power:	Ac220v ±10%,50/60hz
Heater Power:	Upper Temp.one 1600w,second Temp.zone1600w,IR Temp.zone 5000w
Alignment System:	Optical Prism + HD Camera
Highlight:	**high Accuracy BGA Optical Alignment System, Automatic feeding BGA Optical Alignment System , high Accuracy BGA Repair Machine**



More Images



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Product Description

HD display Vacuum adsorption WDS-850 Optical alignment automatic repair equipment

Excellent performance features

Multi-language menu interface
Automatic feeding decive
X/Y axis can be controlled by rocker, fast oeration
Imported high-definition CCD(2 million pixels) optical alignment ststem
High precision temperature control system, accurate temperature control system, accuate temperature control

Specification

WDS-850

Power	AC 220V±10 50Hz	Total power	7600W
Up heater power	Max1200W	Mount max load	800G
Down heater powe	Max1200W	IR power	5000W（2000W controlled）
Max PCB size	630*480mm	Min PCB size	10×10mm
Chip magnification	2-50 multiple	Temp. interface	5个
Suit PCB thickness	0.5-8mm	Mount accuracy	±0.01mm
Suit chip size	0.8*0.8~80*80mm	Chip min spacing	0.15mm
Dimensions	L970*W700*H830mm	Weight	About 210KG

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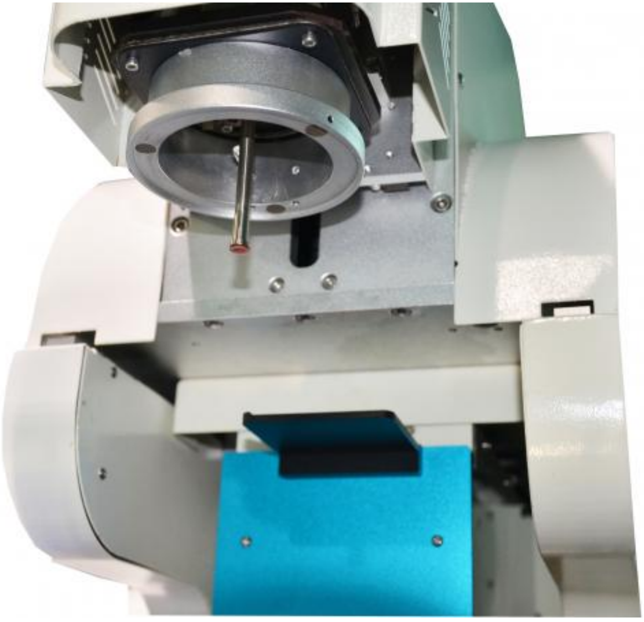
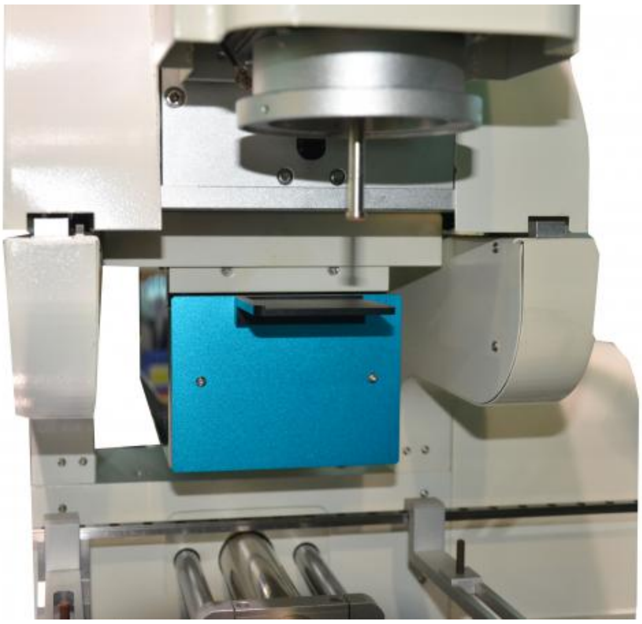


HD optical alignment and intelligent control

The integrated design of hot air head and mounting head has the functions of automatic mounting, automatic welding and automatic disassembly. High precision K-type thermocouple (KSENSOR) cLOSED Loop control, up and down independent temperature measurement, temperature control accuracy up to ± 1 degree, Over-temperature protection alarm function, software encryption and anti-stay function.

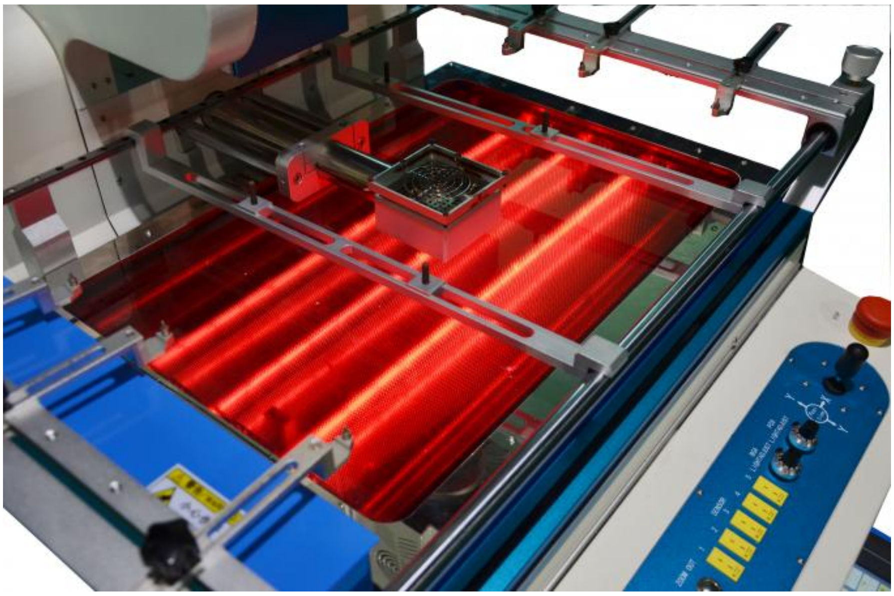


HD display

High-definition imported CCD(2 million pixels) digital imaging, automatic optical zoom system, automatic precision alignment control system with laser red dot, using 15 inch high-definition industrial display screen dispaly.

Vacuum adsorption and preheating platform

The upper heating head is equipped with a vacuum suction pipe for chip adsorption. The bottom preheating platform adopts imported excellent heating materials(infrared gold-plated light tube)+anti-flash thermostatic glass (temperature resistance up to 1800°C). The preheating area is up to 500*420mm. The preheating platform, splint device and cooling system can be moved as a whole in the X direction. Make PCB positioning and folding welding more safe and convenient.



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Specification

Model	WDS-850
Total power supply	8400W
Upper heating power supply	1600W
Lower heating power supply	1600W
IR heating power supply	5000W(2000W controlled)
Power supply	220V, 50/60Hz
Maximum	680*550mm
Minimum	10*10mm
Temperature measuring interfaces	5pcs

Chip zoom in and zoom out	2-50/times
The PCB thickness	0.5 8mm
Apply chip size	0.8*0.8 120*120mm
Applicable minimum chip spacing	0.15mm
Maximum mouting load	300g
Mounting precision	±0.01mm
Machine dimension	L970*W700*H830mm
Machine weight	200KG

Shenzhen Wisdomshow Technology Co.,ltd

☎ +86 17727914291 ✉ Mia@wdsbga.cn ⓔ bgaxraymachine.com

No.6,Haosi Western Industry,Shangjing Town,Bao'an District,Shenzhen,China